



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE5206-2G			<b>Issued</b>	28. August 2013			
<b>MA#</b>	MA000600988							
<b>Package</b>	PG-TO263-7-1			<b>Weight*</b>	1537.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.039	0.72	0.72	7182	7182
leadframe	non noble metal	iron	7439-89-6	0.916	0.06		596	
	inorganic material	phosphorus	7723-14-0	0.275	0.02		179	
	non noble metal	copper	7440-50-8	914.823	59.51	59.59	595165	595940
wire	non noble metal	aluminium	7429-90-5	2.750	0.18	0.18	1789	1789
encapsulation	organic material	carbon black	1333-86-4	8.785	0.57		5716	
	plastics	epoxy resin	-	96.640	6.29		62872	
	inorganic material	silicondioxide	60676-86-0	480.273	31.25	38.11	312456	381044
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8481	8481
plating	non noble metal	nickel	7440-02-0	0.212	0.01		138	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	138
solder	noble metal	silver	7440-22-4	0.208	0.01		136	
	non noble metal	tin	7440-31-5	0.167	0.01		109	
	non noble metal	lead	7439-92-1	7.964	0.52	0.54	5181	5426
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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